

IN THE SPECIFICATION

Please amend the paragraph beginning at page 57, line 3, as follows:

A package substrate 134 (see Fig. 13) has the same basic structure except for the shape of the via hole 7 which is formed into a ring shape as shown in Fig. 13 (B). Fig. 13 (B) is view of B of Fig. 13 (A). As seen in Figs. 13 (A) – 13(B), the planar area of the pad structure is greater than the planar area of the conductive circuit.

Please amend the paragraph beginning at page 57, line 31 and continued on page 58, as follows:

The basic structure is the same as that according to example 2 of the second modification. A package substrate 136 (see Fig. 15) has a structure that the conductor layer to which the pad 16 is connected is made to be a conductor layer (a land 91) provided for the through hole 9 of the core substrate 1. Moreover, the periphery of the pad 16 is covered with the organic resin insulating layer 15. As shown in the drawing, the pad 16 is, through the via hole 7, connected to the land 91 of the through hole 9 and the resin filler 10 in the through hole 9. Further, as with Fig. 13, the planar area of the pad structure is greater than the planar area of the conductive circuit.